#### Static Characteristics @ T<sub>J</sub> = 25°C (unless otherwise stated)

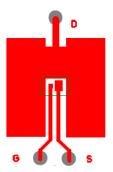
	Parameter	Min.	Тур.	Max.	Units	Conditions
V <sub>(BR)DSS</sub>	Drain-to-Source Breakdown Voltage	40			V	$V_{GS} = 0V, I_D = 250\mu A$
$\Delta V_{(BR)DSS}/\Delta T_{J}$	Breakdown Voltage Temp. Coefficient		0.03		V/°C	Reference to 25°C, I <sub>D</sub> = 1mA
R <sub>DS(on)</sub>	Static Drain-to-Source On-Resistance		1.5	1.9	mΩ	V <sub>GS</sub> = 10V, I <sub>D</sub> = 94A ⑦
$V_{GS(th)}$	Gate Threshold Voltage	2.0	3.0	4.0	V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 150μΑ
$\Delta V_{GS(th)}/\Delta T_J$	Gate Threshold Voltage Coefficient		-10		mV/°C	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 130μA
gfs	Forward Transconductance	100			S	$V_{DS} = 10V, I_{D} = 94A$
R <sub>G</sub>	Gate Resistance		0.6		Ω	
I <sub>DSS</sub>	Drain-to-Source Leakage Current			5		$V_{DS} = 40V, V_{GS} = 0V$
				250	μA	$V_{DS} = 40V, V_{GS} = 0V, T_{J} = 125^{\circ}C$
I <sub>GSS</sub>	Gate-to-Source Forward Leakage			100	nA	$V_{GS} = 20V$
	Gate-to-Source Reverse Leakage			-100	IIA	V <sub>GS</sub> = -20V

# Dynamic Characteristics @ T<sub>J</sub> = 25°C (unless otherwise stated)

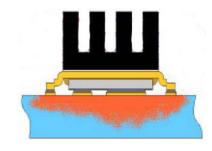
	Parameter	Min.	Тур.	Max.	Units	Conditions
$Q_g$	Total Gate Charge		89	134		$V_{DS} = 20V, V_{GS} = 10V$
Q <sub>gs1</sub>	Pre-Vth Gate-to-Source Charge		18			I <sub>D</sub> = 94A
$Q_{gs2}$	Post-Vth Gate-to-Source Charge		8		nC	See Fig.11
$Q_{gd}$	Gate-to-Drain ("Miller") Charge		34	_		
$Q_godr$	Gate Charge Overdrive		29			
$Q_{sw}$	Switch Charge (Q <sub>gs2</sub> + Q <sub>gd</sub> )	_	42			
Q <sub>oss</sub>	Output Charge	_	39		nC	$V_{DS} = 16V, V_{GS} = 0V$
t <sub>d(on)</sub>	Turn-On Delay Time		12			$V_{DD} = 20V, V_{GS} = 10V$ ⑦
t <sub>r</sub>	Rise Time		19			I <sub>D</sub> = 94A
t <sub>d(off)</sub>	Turn-Off Delay Time		22		ns	$R_G = 1.8\Omega$
t <sub>f</sub>	Fall Time		14			
C <sub>iss</sub>	Input Capacitance		5469			$V_{GS} = 0V$
C <sub>oss</sub>	Output Capacitance		1193			V <sub>DS</sub> = 25V
C <sub>rss</sub>	Reverse Transfer Capacitance		534			f = 1.0MHz
Coss	Output Capacitance		4296		pF	$V_{GS} = 0V, V_{DS} = 1.0V, f=1.0MHz$
Coss	Output Capacitance		1066			$V_{GS} = 0V, V_{DS} = 32V, f=1.0MHz$
C <sub>oss</sub> eff.	Effective Output Capacitance		1615		1	$V_{GS} = 0V$ , $V_{DS} = 0V$ to $32V$

#### Diode Characteristics @ T<sub>J</sub> = 25°C (unless otherwise stated)

	•			-				
	Parameter	Min.	Тур.	Max.	Units	Conditions		
Is	Continuous Source Current	<u> </u>		156		MOSFET symbol		
	(Body Diode)			130	Α	showing the		
I <sub>SM</sub>	Pulsed Source Current					integral reverse		
	(Body Diode) S			624		p-n junction diode.	s	
V <sub>SD</sub>	Diode Forward Voltage			1.3	V	I <sub>S</sub> = 94A, V <sub>GS</sub> = 0V ⑦		
t <sub>rr</sub>	Reverse Recovery Time		35	53	ns	$I_F = 94A, V_{DD} = 20V$		
Q <sub>rr</sub>	Reverse Recovery Charge		32	48	nC	di/dt = 100A/µs ⑦		



③ Surface mounted on 1 in. square Cu (still air).



Mounted to a PCB with small clip heatsink (still air)



 Mounted on minimum footprint full size board with metalized back and with small clip heatsink (still air)

Notes ① through ⑩ are on page 10

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#### Qualification Information<sup>†</sup>

		Automotive				
			(per AEC-Q101) <sup>††</sup>			
Qualification Level		Comments: This part number(s) passed Automotive qualification IR's Industrial and Consumer qualification level is granted b extension of the higher Automotive level.				
Moisture Sensitivity Level		LARGE-CAN MSL1				
	Machine Model	Class M4(+/-425V)				
		(per AEC-Q101-002)				
	Human Body Model	Class H1C(+/-2000V)				
ESD		(per AEC-Q101-001)				
	Charged Device	N/A				
	Model	(per AEC-Q101-005)				
RoHS Compliant	*	Yes				

<sup>†</sup> Qualification standards can be found at International Rectifier's web site: <a href="http://www.irf.com">http://www.irf.com</a>

<sup>††</sup> Exceptions to AEC-Q101 requirements are noted in the qualification report.

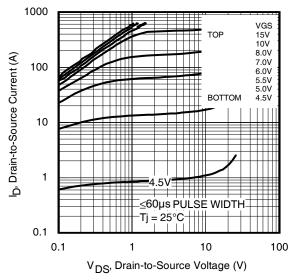
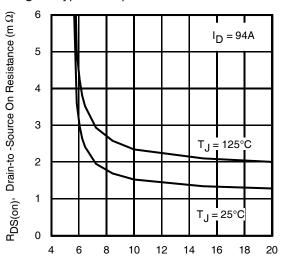
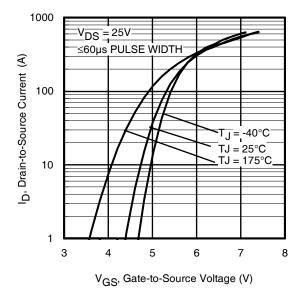


Fig 1. Typical Output Characteristics



V<sub>GS,</sub> Gate -to -Source Voltage (V) **Fig 3.** Typical On-Resistance vs. Gate Voltage



**Fig 5.** Typical Transfer Characteristics 4

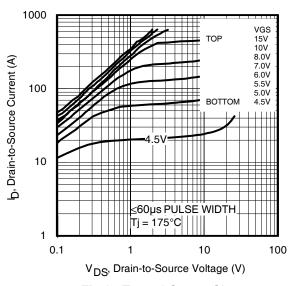


Fig 2. Typical Output Characteristics

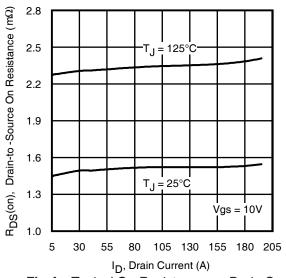
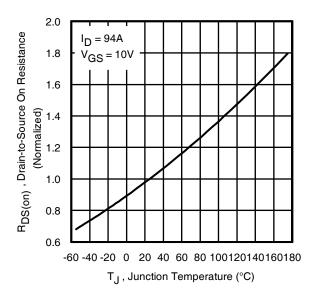
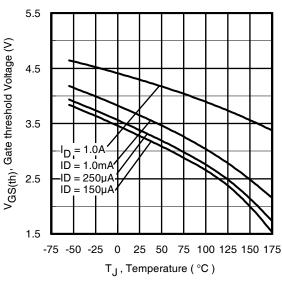


Fig 4. Typical On-Resistance vs. Drain Current



**Fig 6.** Normalized On-Resistance vs. Temperature www.irf.com



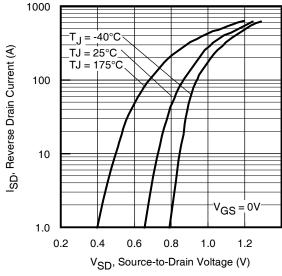
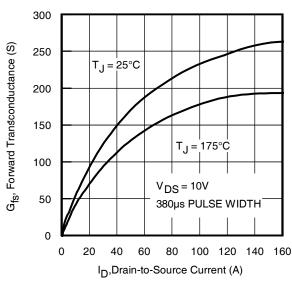


Fig 7. Typical Threshold Voltage vs. Junction Temperature

Fig 8. Typical Source-Drain Diode Forward Voltage



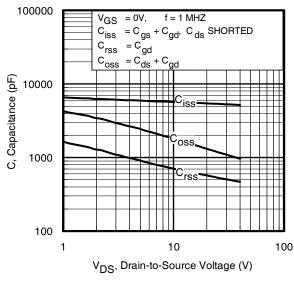
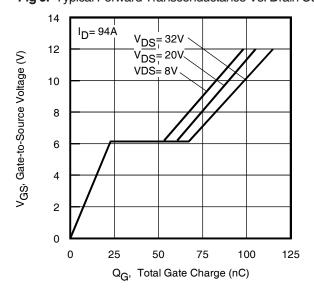
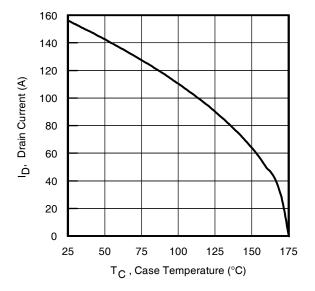


Fig 9. Typical Forward Transconductance Vs. Drain Current

Fig 10. Typical Capacitance vs.Drain-to-Source Voltage





**Fig.11** Typical Gate Charge vs.Gate-to-Source Voltage www.irf.com

Fig 12. Maximum Drain Current vs. Case Temperature

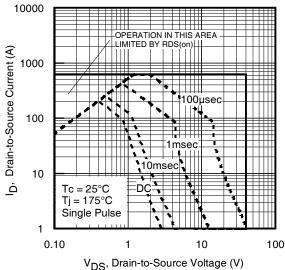
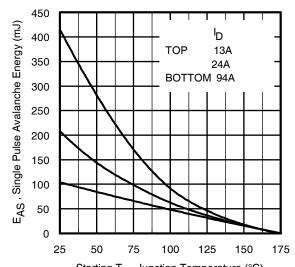


Fig 13. Maximum Safe Operating Area



 $\label{eq:StartingTJ} \mbox{Starting T}_{\mbox{\scriptsize J}} \,, \, \mbox{Junction Temperature (°C)}$   $\mbox{Fig 14.} \ \mbox{Maximum Avalanche Energy vs. Temperature}$ 

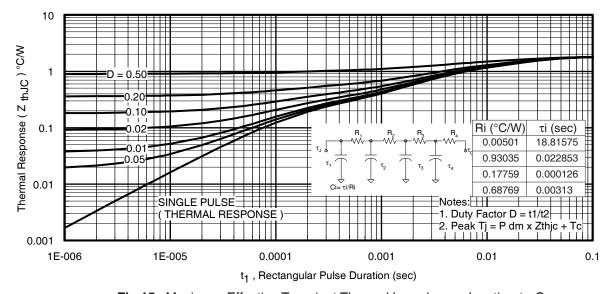


Fig 15. Maximum Effective Transient Thermal Impedance, Junction-to-Case

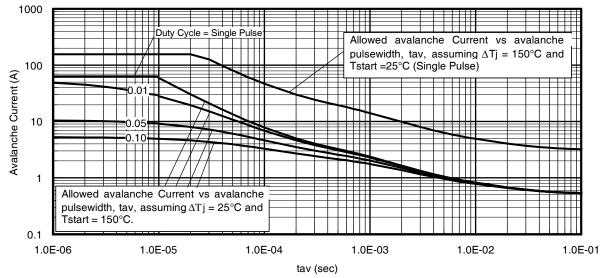


Fig 16. Typical Avalanche Current Vs.Pulsewidth

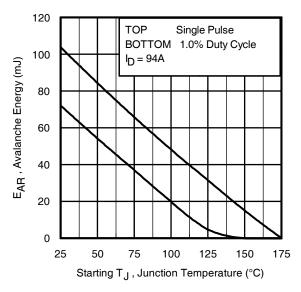


Fig 17. Maximum Avalanche Energy Vs. Temperature

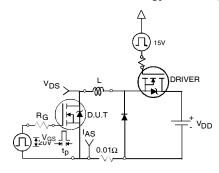


Fig 18a. Unclamped Inductive Test Circuit

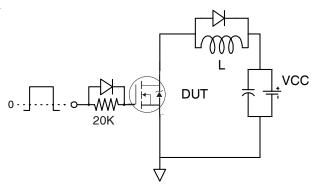


Fig 19a. Gate Charge Test Circuit

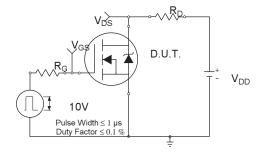


Fig 20a. Switching Time Test Circuit

Notes on Repetitive Avalanche Curves , Figures 16, 17: (For further info, see AN-1005 at www.irf.com)

- 1. Avalanche failures assumption: Purely a thermal phenomenon and failure occurs at a temperature far in excess of  $T_{jmax}$ . This is validated for
- 2. Safe operation in Avalanche is allowed as long  $asT_{imax}$  is not exceeded.
- 3. Equation below based on circuit and waveforms shown in Figures 18a, 18b.
- 4. P<sub>D (ave)</sub> = Average power dissipation per single avalanche pulse.
- 5. BV = Rated breakdown voltage (1.3 factor accounts for voltage increase during avalanche).
- 6. I<sub>av</sub> = Allowable avalanche current.
- 7.  $\Delta T$  = Allowable rise in junction temperature, not to exceed T<sub>jmax</sub> (assumed as 25°C in Figure 16, 17).
  - t<sub>av =</sub> Average time in avalanche.
  - D = Duty cycle in avalanche =  $t_{av} \cdot f$

 $Z_{th,IC}(D, t_{av})$  = Transient thermal resistance, see figure 15)

$$\begin{split} P_{D\;(ave)} &= 1/2\;(\;1.3 \cdot BV \cdot I_{av}) = \Delta T/\;Z_{thJC} \\ I_{av} &= 2\Delta T/\;[1.3 \cdot BV \cdot Z_{th}] \\ E_{AS\;(AR)} &= P_{D\;(ave)} \cdot t_{av} \end{split}$$

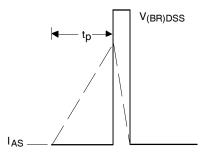


Fig 18b. Unclamped Inductive Waveforms

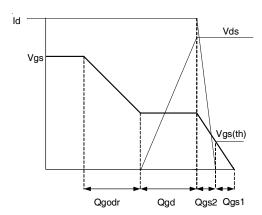


Fig 19b. Gate Charge Waveform

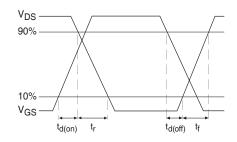
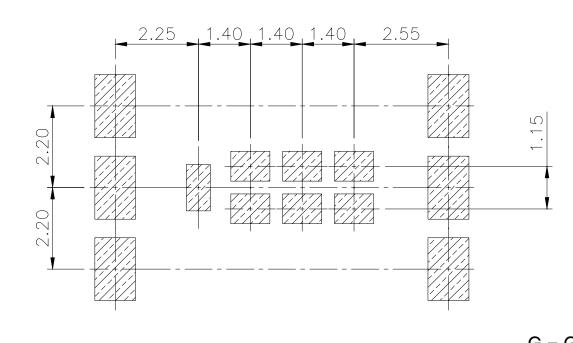
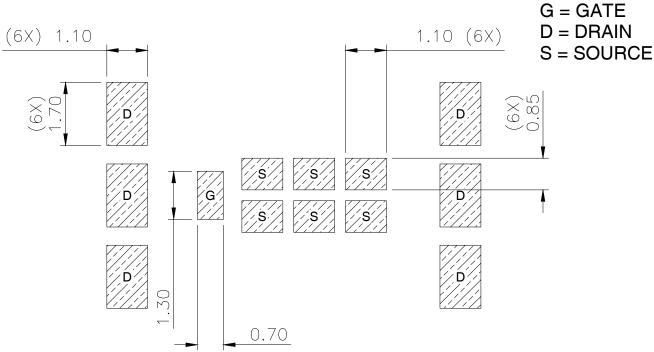


Fig 20b. Switching Time Waveforms

### Automotive DirectFET® Board Footprint, L6 (Large Size Can).

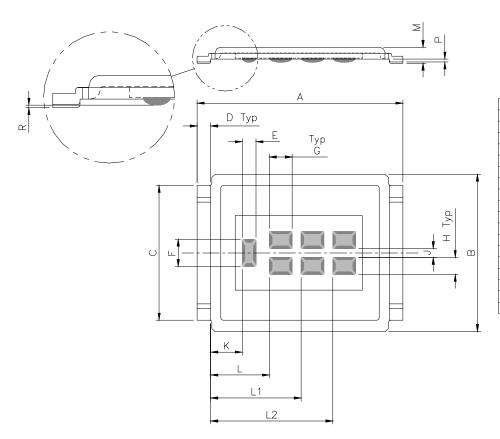
Please see AN-1035 for DirectFET® assembly details and stencil and substrate design recommendations





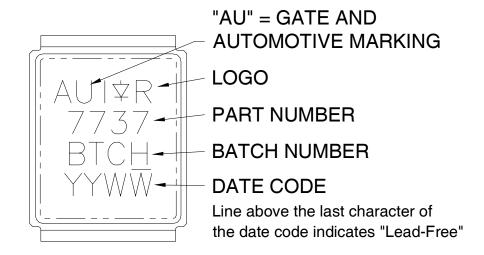
# Automotive DirectFET® Outline Dimension, L6 Outline (LargeSize Can).

Please see AN-1035 for DirectFET® assembly details and stencil and substrate design recommendations



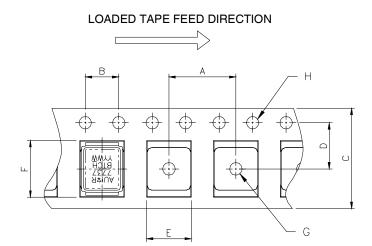
DIMENSIONS							
	MET	TRIC	IMPE	RIAL			
CODE	MIN	MAX	MIN	MAX			
Α	9.05	9.15	0.356	0.360			
В	6.85	7.10	0.270	0.280			
С	5.90	6.00	0.232	0.236			
D	0.55	0.65	0.022	0.026			
Е	0.58	0.62	0.023	0.024			
F	1.18	1.22	0.046	0.048			
G	0.98	1.02	0.039	0.040			
Н	0.73	0.77	0.029	0.030			
J	0.38	0.42	0.015	0.017			
K	1.35	1.45	0.053	0.057			
L	2.55	2.65	0.100	0.104			
L1	3.95	4.05	0.155	0.159			
L2	5.35	5.45	0.210	0.214			
M	0.68	0.74	0.027	0.029			
Р	0.09	0.17	0.003	0.007			
R	0.02	0.08	0.001	0.003			

### Automotive DirectFET® Part Marking



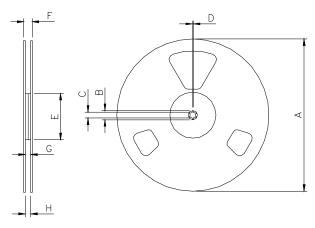
Note: For the most current drawing please refer to IR website at <a href="http://www.irf.com/package/">http://www.irf.com/package/</a>

# Automotive DirectFET® Tape & Reel Dimension (Showing component orientation).



NOTE: CONTROLLING DIMENSIONS IN MM

DIMENSIONS								
	MET	TRIC	IMPERIAL					
CODE	MIN	MAX	MIN	MAX				
Α	11.90	12.10	4.69	0.476				
В	3.90	4.10	0.154	0.161				
С	15.90 16.30		0.623	0.642				
D	7.40	7.60	0.291	0.299				
E	7.20	7.40	0.283	0.291				
F	9.90	10.10	0.390	0.398				
G	1.50	N.C	0.059	N.C				
Н	1.50	1.60	0.059	0.063				



NOTE: Controlling dimensions in mm Std reel quantity is 4000 parts. (ordered as AUIRF7737L2TR). For 1000 parts on 7" reel, order AUIRF7737L2TR1

	REEL DIMENSIONS								
STANDARD OPTION (QTY 4000)					TR1 OPTION (QTY 1000)				
	MET	RIC	IMPERIAL		MET	RIC	IMPERIAL		
CODE	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
Α	330.00	N.C	12.992	N.C	177.80	N.C	7.000	N.C	
В	20.20	N.C	0.795	N.C	20.20	N.C	0.795	N.C	
С	12.80	13.20	0.504	0.520	12.98	13.50	0.331	0.50	
D	1.50	N.C	0.059	N.C	1.50	2.50	0.059	N.C	
Е	99.00	100.00	3.900	3.940	62.48	N.C	2.460	N.C	
F	N.C	22.40	N.C	0.880	N.C	N.C	N.C	0.53	
G	16.40	18.40	0.650	0.720	N.C	N.C	N.C	N.C	
Н	15.90	19.40	0.630	0.760	16.00	N.C	0.630	N.C	

#### Notes:

- ① Click on this section to link to the appropriate technical paper.
- ② Click on this section to link to the DirectFET® Website.
- 3 Surface mounted on 1 in. square Cu board, steady state.
- $\ensuremath{\mathfrak{G}}$   $T_C$  measured with thermocouple mounted to top (Drain) of part.
- ⑤ Repetitive rating; pulse width limited by max. junction temperature.
- © Starting  $T_J = 25^{\circ}C$ , L = 0.024mH,  $R_G = 50\Omega$ ,  $I_{AS} = 94A$ .
- $\ensuremath{{\bigcirc}}$  Pulse width  $\le 400 \mu s;$  duty cycle  $\le 2\%.$
- ® Used double sided cooling, mounting pad with large heatsink.
- Mounted on minimum footprint full size board with metalized back and with small clip heatsink.
- $^{\circledR}$  R $_{\theta}$  is measured at T $_{J}$  of approximately 90°C.

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